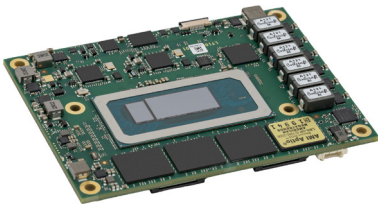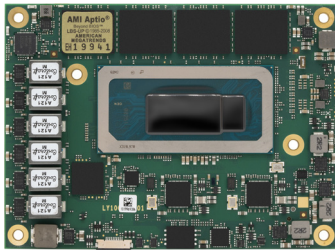# TRIA COM-HPC Mini module with 13th Gen Intel® Core™ processor

Powerful Edge Computing for Transportation, Medical, Automation, and Robotics

TRIA is extending its large product portfolio of embedded Computer on Modules by introducing the HMM-RLP, a COM-HPC Mini module based on the 13th Gen Intel® Core™ processor.

COM-HPC Mini offers the advantage of integrating high-performant processors with high degree of IO connectivity and bandwidth on a small embedded form factor. Module products based on the standard are a perfect fit in applications, that require solid performance and bandwidth in space and cooling constraint applications. Applications in transportation, instrumentation, medical, automation and robotics can utilize the scalability of performance and I/O, the 13th Gen Intel® Core™ processors provide.

Key Features

High Performance	Ruggedized Design	Extensive I/O Connectivity	Scalable and Versatile

Intel Products & Technology

Intel® Core™ Processors

Intel® Core™ processors deliver high-performance computing for various applications, offering advanced AI acceleration, power efficiency, and seamless multitasking across consumer, commercial, and industrial devices.